

Tx/Rx – Layout (22nm SOI)

Customer : The customer is a tier-1 company.

Project : High Speed Tx and Rx in 22nm intended to work above 50GHz.

Mirafra's Responsibility : Mirafra handled layout ownership from area estimation to final handoff.

- Chip area estimation along with pad frame placement.
- Chip level floor plan with critical discussion with chip lead as per the signal flow .
- Chip level power plan taking into account the current and IR drop requirements of modules.
- Area estimation/floor plan of sub blocks
- Module level routing and full chip hook up
- Two level review with signal and power plan
- Final hand off after review updates and checkers

Tools used : Virtuoso (Cadence)

Engagement Model : A team of 2 people in ODC based on T&M model.